

ABSTRACT OF THE DISCLOSURE

The present invention provides a method for manufacturing an electronic component of laminated ceramics such as a laminated ceramic capacitor in which, when a ceramic paste is applied on a ceramic green sheet in order to substantially eliminate steps caused by the thickness of a film of inner circuit elements such as an inner electrode, the ceramic paste is prevented from generating a gap between the paste and the film of inner circuit elements, or the thickness of the ceramic paste is prevented from being increased, by allowing the paste to overflow the film of inner circuit elements, even when the application position has been a little shifted, wherein an inclined face is formed at the periphery of an inner electrode that serves as the film of inner circuit elements, the ceramic paste being applied so as to overlap the periphery of the inner electrode, and wherein the used ceramic paste contains 40% by weight to 85% by weight of solvents in order to facilitate smooth leveling of the applied ceramic paste.

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